



Material Content Data Sheet



Sales Product Name		BTS432E2		Issued		19. January 2018		
MA#		MA001813266						
Package		PG-TO220-5-11		Weight*		2112.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	13.065	0.62	0.62	6186	6186
leadframe	inorganic material	phosphorus	7723-14-0	0.277	0.01		131	
	non noble metal	iron	7439-89-6	0.923	0.04		437	
	non noble metal	copper	7440-50-8	921.567	43.63	43.68	436317	436885
	non noble metal	aluminium	7429-90-5	1.556	0.07	0.07	737	737
wire	non noble metal	aluminium	7429-90-5	1.556	0.07	0.07	737	737
encapsulation	organic material	carbon black	1333-86-4	6.045	0.29		2862	
	inorganic material	antimonytrioxide	1309-64-4	12.640	0.60		5984	
	plastics	brominated resin	-	14.288	0.68		6765	
	plastics	epoxy resin	-	104.415	4.94		49436	
	inorganic material	silicondioxide	60676-86-0	412.165	19.51	26.02	195141	260188
leadfinish	non noble metal	tin	7440-31-5	24.181	1.14	1.14	11449	11449
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		4	
	non noble metal	nickel	7440-02-0	3.285	0.16	0.16	1555	1559
glue	plastics	Polyimide	26023-21-2	0.410	0.02	0.02	194	194
solder	non noble metal	tin	7440-31-5	0.142	0.01		67	
	noble metal	silver	7440-22-4	0.177	0.01		84	
	non noble metal	lead	7439-92-1	6.767	0.32	0.34	3204	3355
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		84	
	non noble metal	iron	7439-89-6	0.590	0.03		279	
	non noble metal	copper	7440-50-8	589.466	27.91	27.95	279084	279447
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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